N-Channel 30 V (D-S) MOSFET

PowerPAK® SC-70-6L Single

Top View

Bottom View

Marking Code: AS

FEATURES

- TrenchFET® power MOSFET
- 100 % R_g tested
- Material categorization:
  for definitions of compliance please see
  www.vishay.com/doc?99912

APPLICATIONS

- DC/DC converters and synchronous buck converters
  - Lower ringing voltage from soft turn-on
  - High efficiency from fast turn-off
  - Lower shoot-through possibility

Pb-free
RoHS COMPLIANT
HALOGEN FREE

N-Channel MOSFET

PRODUCT SUMMARY

V_{DS} (V)	30
$R_{DS(on)}$ max. (Ω) at V_{GS} = 10 V	0.018
$R_{DS(on)}$ max. (Ω) at V_{GS} = 6 V	0.020
$R_{DS(on)}$ max. (Ω) at V_{GS} = 4.5 V	0.022
Q_g typ. (nC)	5
I_D (A) [a]	12
Configuration	Single
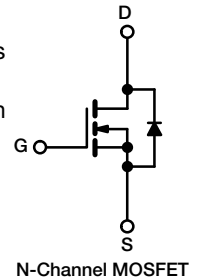
ORDERING INFORMATION

Package	PowerPAK SC-70
Lead (Pb)-free and halogen-free	SiA462DJ-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	30	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current (T_J = 150 °C)	T_C = 25 °C	I_D	12 [a]	A
	T_C = 70 °C		12 [a]	
	T_A = 25 °C		12 [a, b, c]	
	T_A = 70 °C		9.7 [b, c]	
Pulsed drain current (t = 300 μs)		I_{DM}	40	
Continuous source-drain diode current	T_C = 25 °C	I_S	12 [a]	
	T_A = 25 °C		2.9 [b, c]	
Maximum power dissipation	T_C = 25 °C	P_D	19	W
	T_C = 70 °C		12	
	T_A = 25 °C		3.5 [b, c]	
	T_A = 70 °C		2.2 [b, c]	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) [d, e]			260	

THERMAL RESISTANCE RATINGS

PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient [b, f]	t ≤ 5 s	R_{thJA}	28	36	°C/W
Maximum junction-to-case (drain)	Steady state	R_{thJC}	5.3	6.5	

Notes
a. Based on package limited
b. Surface mounted on 1" x 1" FR4 board
c. t = 5 s
d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
f. Maximum under steady state conditions is 80 °C/W

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)

| PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	30	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA	-	34	-	mV/°C
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	-5	-	
Gate-source threshold voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1.2	-	2.4	V
Gate-source leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} = 30 V, V_{GS} = 0 V	-	-	1	µA
		V_{DS} = 30 V, V_{GS} = 0 V, T_J = 55 °C	-	-	10	
On-state drain current [a]	$I_{D(on)}$	$V_{DS} \geq$ 5 V, V_{GS} = 10 V	10	-	-	A
Drain-source on-state resistance [a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 9 A	-	0.015	0.018	Ω
		V_{GS} = 6 V, I_D = 7 A	-	0.016	0.020	
		V_{GS} = 4.5 V, I_D = 7 A	-	0.018	0.022	
Forward transconductance [a]	g_{fs}	V_{DS} = 10 V, I_D = 9 A	-	35	-	S
Dynamic [b]						
Input capacitance	C_{iss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	-	570	-	pF
Output capacitance	C_{oss}		-	126	-	
Reverse transfer capacitance	C_{rss}		-	52	-	
Total gate charge	Q_g	V_{DS} = 15 V, V_{GS} = 10 V, I_D = 12 A	-	11	17	nC
		V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 12 A	-	5	7.5	
Gate-source charge	Q_{gs}		-	1.7	-	
Gate-drain charge	Q_{gd}		-	1.6	-	
Gate resistance	R_g	f = 1 MHz	0.2	1	2	Ω
Turn-on delay time	$t_{d(on)}$	V_{DD} = 15 V, R_L = 1.5 Ω, $I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω	-	5	10	ns
Rise time	t_r		-	10	20	
Turn-off delay time	$t_{d(off)}$		-	15	30	
Fall time	t_f		-	10	20	
Turn-on delay time	$t_{d(on)}$	V_{DD} = 15 V, R_L = 1.5 Ω, $I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω	-	12	25	
Rise time	t_r		-	15	30	
Turn-off delay time	$t_{d(off)}$		-	15	30	
Fall time	t_f		-	10	20	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	T_C = 25 °C	-	-	12	A
Pulse diode forward current [a]	I_{SM}		-	-	40	
Body diode voltage	V_{SD}	I_S = 10 A	-	0.85	1.2	V
Body diode reverse recovery time	t_{rr}	I_F = 10 A, di/dt = 100 A/µs, T_J = 25 °C	-	20	40	ns
Body diode reverse recovery charge	Q_{rr}		-	11	20	nC
Reverse recovery fall time	t_a		-	12	-	ns
Reverse recovery rise time	t_b		-	8	-	

Notes

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
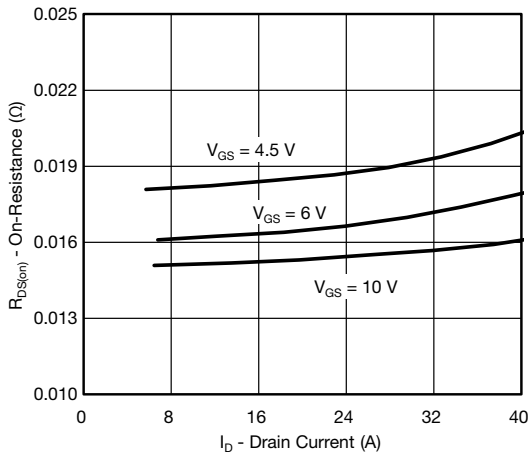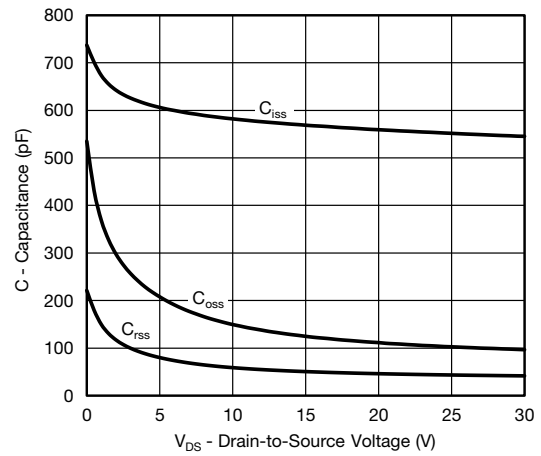
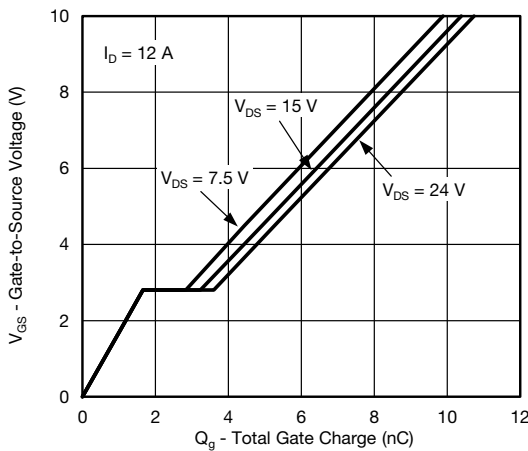**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)
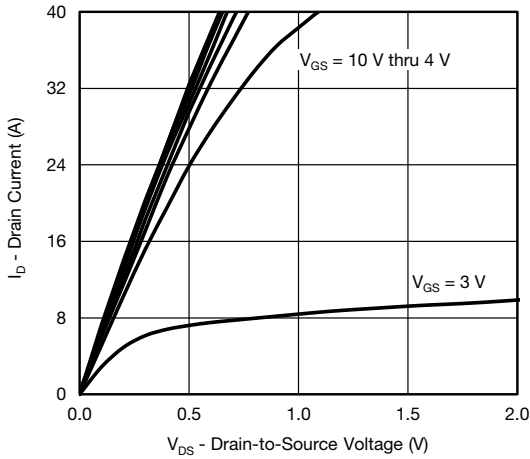
Output Characteristics
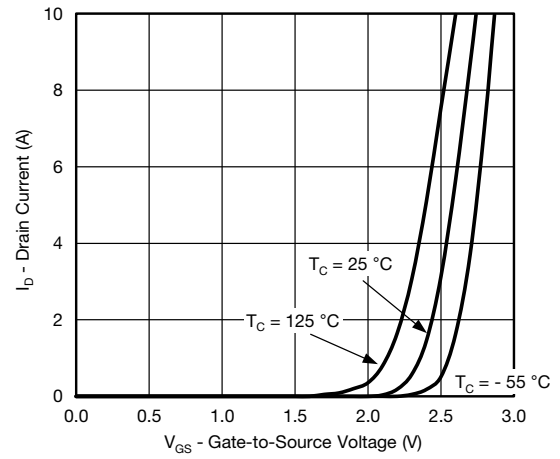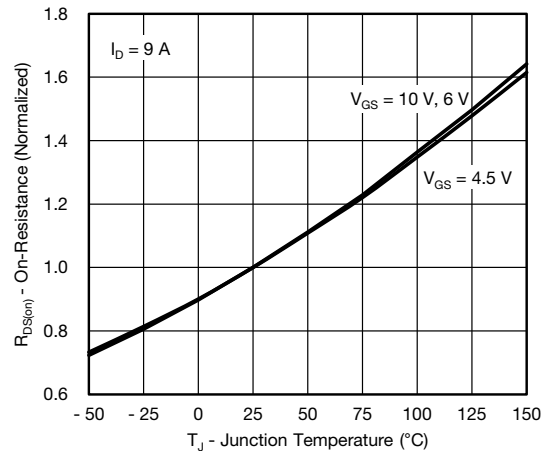

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage
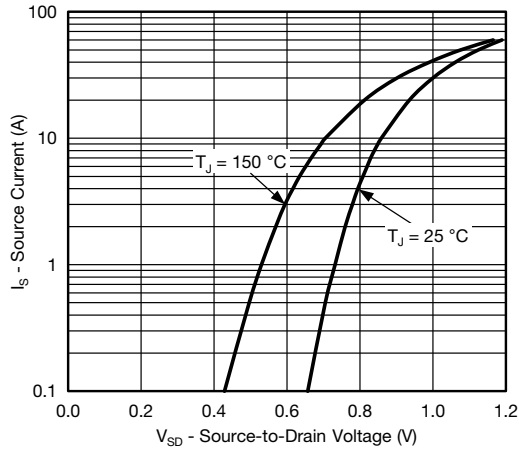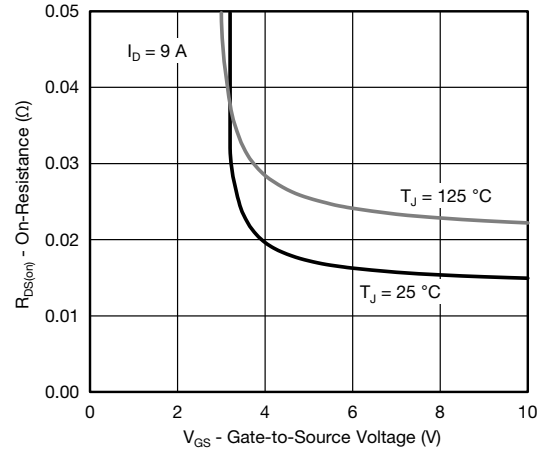

Capacitance

Gate Charge

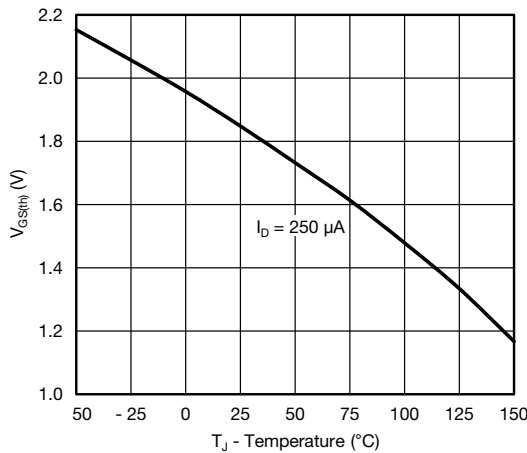**On-Resistance vs. Junction Temperature**

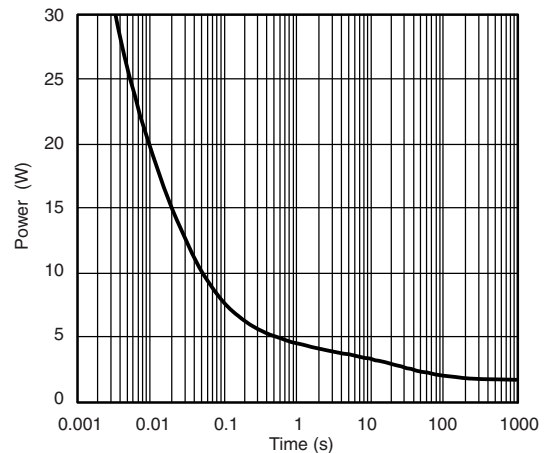**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

Source-Drain Diode Forward Voltage

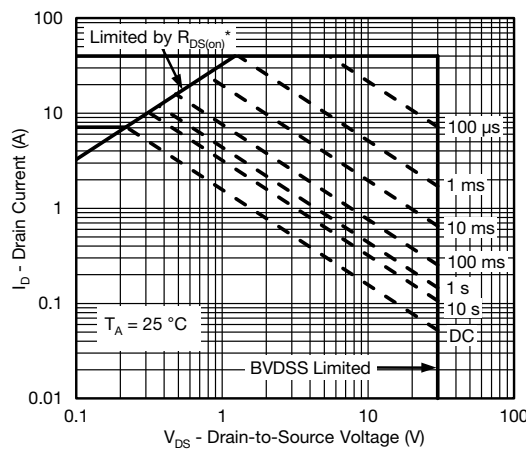On-Resistance vs. Gate-to-Source Voltage
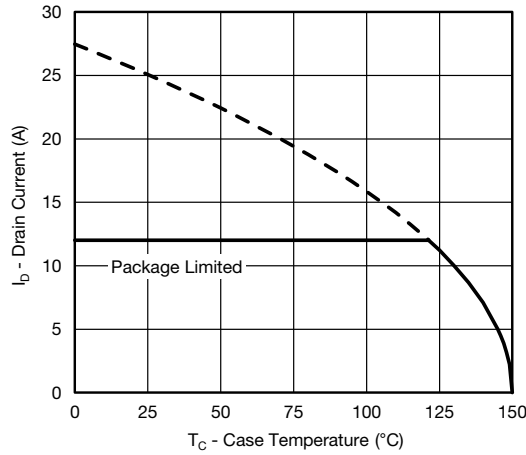

Threshold Voltage

Single Pulse Power, Junction-to-Ambient

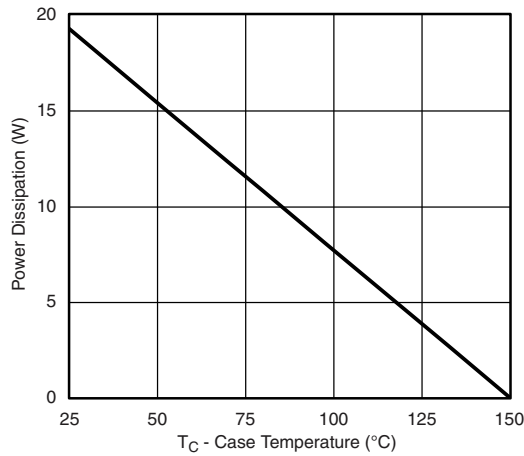* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Ambient

Notes:

1. Duty Cycle, D = $\dfrac{t_1}{t_2}$
2. Per Unit Base = R_{thJA} = 80 °C/W
3. $T_{JM} - T_A = P_{DM}Z_{thJA}^{(t)}$
4. Surface Mounted

Normalized Thermal Transient Impedance, Junction-to-Case
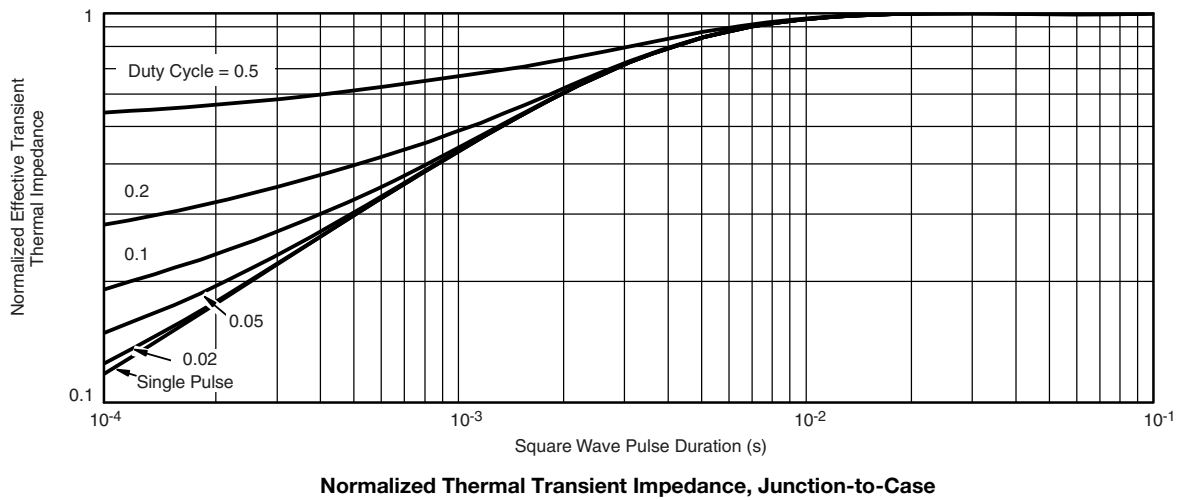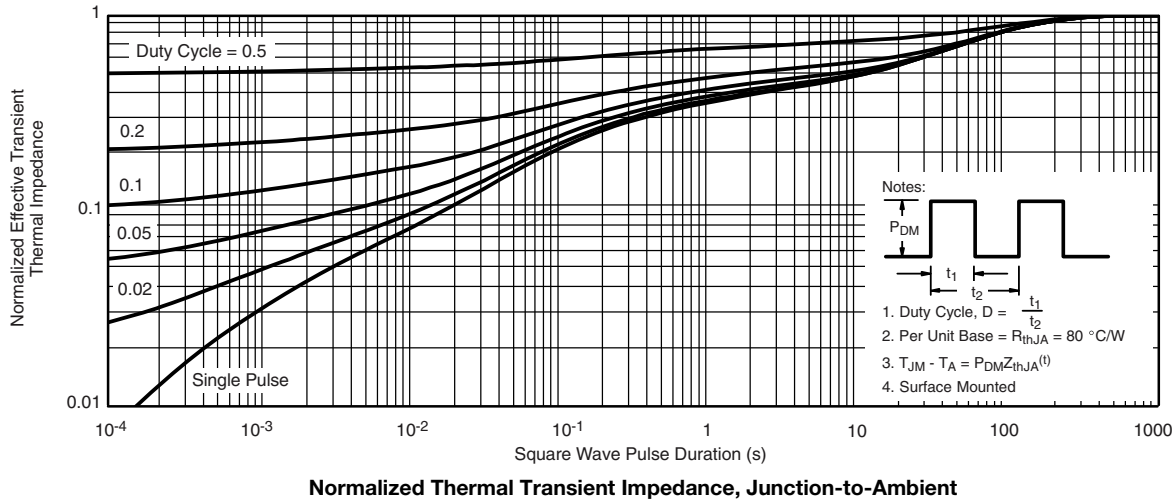
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PowerPAK® SC70-6L
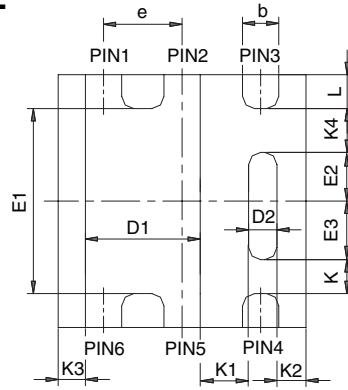
BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL

Notes:
1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

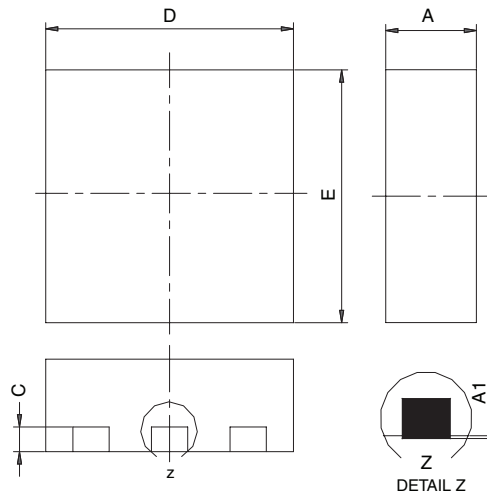DETAIL Z

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006

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DWG: 5934

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single

Dimensions in mm/(Inches)

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APPLICATION NOTE

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